



# THERMCO 8100 AND 8200 PRODUCTION RANGE FURNACE SYSTEMS

## OVERVIEW

Thermco's Model 8100 and 8200 Diffusion Furnaces are configurable from two to four-process chamber systems used for processing Semiconductor, PV, LED, Nano and MEMS substrates up to 200 mm in diameter.

8100 series having 620 mm flatzone and the 8200 series having 1,200mm flatzone, leading to greater wafer processing capacity for the 8200. The 8100 and 8200 can be interfaced to a wide range of automation solutions, such as elevators and fully automatic cassette to cassette automation packages. Automation is recommended for these systems.

The furnace mainframe is constructed of welded and formed cold rolled steel, painted with industrial grade water based enamel paint. Parts and components that are subjected to elevated temperatures are constructed from stainless steel.

## CHARACTERISED PROCESSES:

- Silicon Nitride
- Low Stress Silicon Nitride
- Ramped Temp Polysilicon
- Uniform grain Polysilicon
- TEOS
- LTO (Doped / Undoped)
- BPSG
- High temperature Oxide (HTO)
- High Vacuum H<sub>2</sub> Anneal
- Dry Oxide
- Wet Oxide
- POCl<sub>3</sub> or BBr<sub>3</sub>
- Forming gas anneal
- High temperature drive in
- Alloy or low temp anneal
- 100% H<sub>2</sub> anneal
- FGA Anneal
- CNT growth
- Graphene growth

\* Others available on request

# Thermco Systems have thermal process tools designed with your emerging technologies in mind



## CONTROL SYSTEM

The furnace is controlled by the industry leading Thermco TMX controller, recognised as one of the most flexible and reliable furnace control systems available with an installed base of thousands of units. The TMX control system and PCMUX combines the tried and trusted recipe and system control formats of earlier generation TMX products with new updated, reliable software on PC based hardware with improved graphic, control and AI functions. The system comprises one MUX computer for recipe generation and status overview and one control computer per tube.

## FURNACE PERFORMANCE:

- 3 independently controlled heating zones
- Isolated secondary voltage power
- Zero Cross Over full phase SCR firing
- Balanced power loading
- Thermal safety circuits and SCR cooling fans
- Optional fast ramp (up to 25°C/min), fast cool system (up to 20°C/min)

## OPERATION RANGES:

- Operating temperature range: 200°C to 1350°C
- Low to mid temperature operating range: 200°C to 900°C
- High temperature operating range: 750°C to 1350°C
- R-Type TC's for low to mid temperature range
- B-Type TC's for high temperature range
- Spike and profile temperature control thermocouples
- Cold junction compensation
- Flatzone, 8100 : Up to 640 mm
- Flatzone, 8200 : Up to 1,200 mm



## GAS SYSTEM:

- High quality, ultra clean gas systems with POU filtration
- Regulation and filtration of incoming bulk gases
- Maximum 8 Digital or analogue MFC's
- Orbital welding and VCR fittings
- Nupro air operated valves and check-valves
- Systems tested to 10<sup>-8</sup> ATM cc/sec
- Leak checked to 10<sup>-7</sup> cc/sec



Thermco Systems is a market leading manufacturer of Semiconductor Production Equipment (SPE).

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